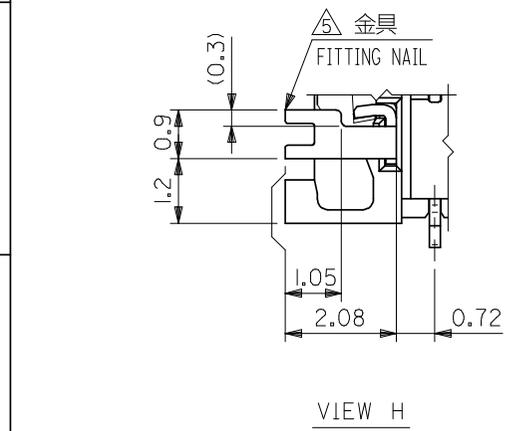
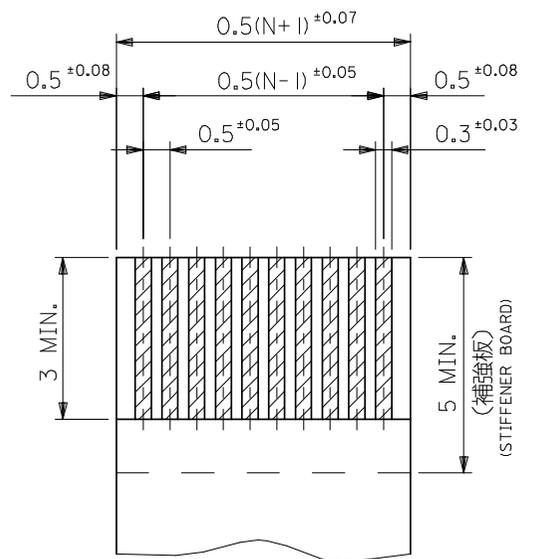
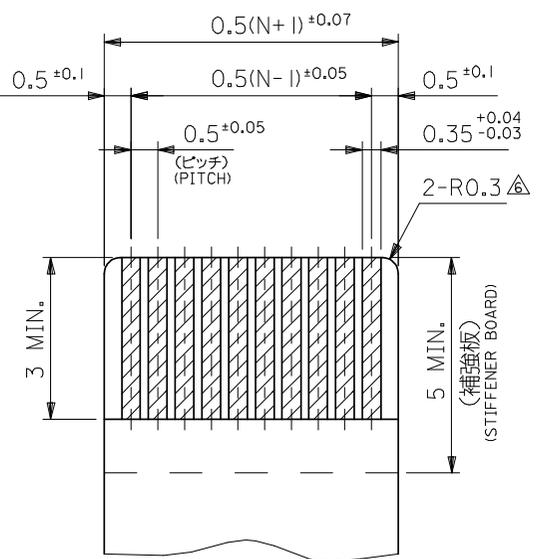
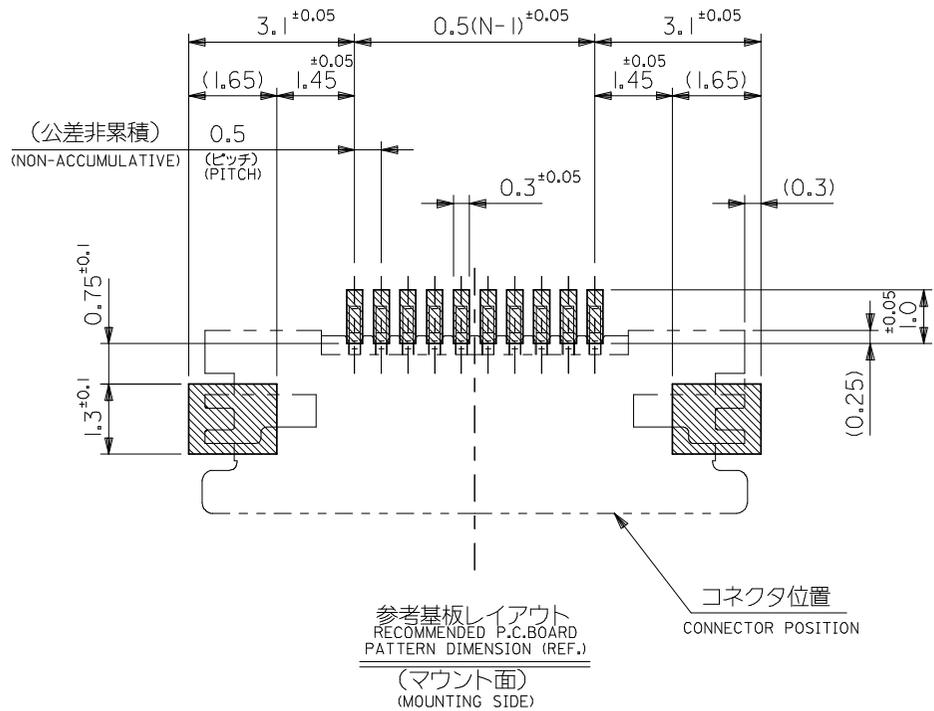


0.28 ±0.03	13.65	17	12.5	18.2	54548-2670	54548-2619	26
	12.65	16	11.5	17.2	54548-2470	54548-2419	24
	11.65	15	10.5	16.2	54548-2270	54548-2219	22
	11.15	14.5	10	15.7	54548-2170	54548-2119	21
	10.65	14	9.5	15.2	54548-2070	54548-2019	20
	10.15	13.5	9	14.7	54548-1970	54548-1919	19
	9.65	13	8.5	14.2	54548-1870	54548-1819	18
	9.15	12.5	8	13.7	54548-1770	54548-1719	17
	8.65	12	7.5	13.2	54548-1670	54548-1619	16
	8.15	11.5	7	12.7	54548-1570	54548-1519	15
	7.65	11	6.5	12.2	54548-1470	54548-1419	14
	7.15	10.5	6	11.7	54548-1370	54548-1319	13
	6.65	10	5.5	11.2	54548-1270	54548-1219	12
	6.15	9.5	5	10.7	54548-1170	54548-1119	11
5.65	9	4.5	10.2	54548-1070	54548-1019	10	
5.15	8.5	4	9.7	54548-0970	54548-0919	9	
4.65	8	3.5	9.2	54548-0870	54548-0819	8	
4.15	7.5	3	8.7	54548-0770	54548-0719	7	
3.65	7	2.5	8.2	54548-0670	54548-0619	6	
3.15	6.5	2	7.7	54548-0570	54548-0519	5	
2.65	6.0	1.5	7.2	54548-0470	54548-0419	4	
THICKNESS OF FPC	D	C	B	A	EMBOSSED TAPE ORDER No. オ-ダ-番	製品番号 MATERIAL No.	極数 CIRCUIT



REVISED EC NO: J2008-4048 DRWN:WABEI 2008/06/13 CHKD:THARYAMA 2008/06/16 APPR:NUKITA 2008/06/16	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1		DESIGN UNITS METRIC		THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY	DATE	TITLE					
	10 OVER 30 UNDER	±0.25	Y. WADA	2004/01/09	0.5 FPC CONN ZIF HSG ASSY FOR SMT RA BTM CONT -LEAD FREE-					
	30 OVER	±0.3	M. SASAO	2004/01/09						
	ANGULAR ±3°		APPROVED BY		DATE		MATERIAL NO.		DOCUMENT NO.	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		M. SASAO		2004/01/09		SEE TABLE		SD-54548-037		
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				SIZE A3		SHEET NO. 1 OF 2				



参考基板レイアウト
RECOMMENDED P.C.BOARD
PATTERN DIMENSION (REF.)
(マウント面)
(MOUNTING SIDE)

コネクタ位置
CONNECTOR POSITION

適合FPC推奨寸法
APPLICABLE FPC
RECOMMENDED DIMENSION
(仕上がり厚さ:表参照)
(THICKNESS:SEE CHART)

適合FFC推奨寸法
APPLICABLE FFC
RECOMMENDED DIMENSION
(仕上がり厚さ:表参照)
(THICKNESS:SEE CHART)

注記 NOTES

1. 使用材料 MATERIAL
ハウジング : LCP, UL94V-0
HOUSING
アクチュエータ : PPS, UL94V-0
ACTUATOR
ターミナル : リン青銅 (t=0.2)、ニッケル下地 鍍ビスマスマッキ
TERMINAL PHOSPHOR BRONZE, TIN-BISMUTH OVER NICKEL PLATING.
金具 : リン青銅 (t=0.2)、ニッケル下地 鍍メッキ
FITTING NAIL PHOSPHOR BRONZE, PURE-TIN OVER NICKEL PLATING.
2. エンボステーブ梱包時は、アクチュエータがロックした状態とする。
IN THE PACKAGE, ACTUATOR OF PART NO.54548-**19 SHOULD BE LOCKED.
- △ ソルダータール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面 Z に対し上方向 0 MAX.、下方向 0.15 MAX. とし
相互のバラツキ量は 0.1 MAX. とする。
MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM Z
UPPER DIRECTION: 0 MAX., LOWER DIRECTION: 0.15 MAX.
OFFSET BETWEEN UPPER AND LOWER 0.1 MAX.
- △ 偶数極に適用。
APPLY FOR EVEN CIRCUIT.
- △ パターンはくり止め用金具
FITTING NAIL FOR PREVENTION OF PEELING
OF P.C.B. PATTERN.
- △ R0.3はFPC導体部にかからないこと
R0.3 MUST NOT BE OVERLAPPED TO PATTERN OF FPC.
7. N: 極数 N: CIRCUIT.

FPC/FFC について:

打ち抜き方向は導体側から補強板側を推奨します。
導体部については軟銅箔35μmまたは50μmを推奨します。

ABOUT FPC/FFC
RECOMMENDED PUNCHER DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.
RECOMMENDED CONDUCTOR SPEC :
THICKNESS OF SOFT COPPER FOIL : 35 MICROMETER OR 50 MICROMETER.

FPC について:

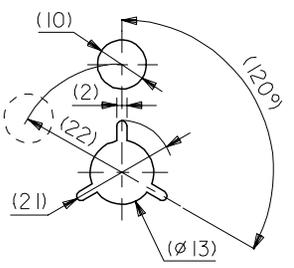
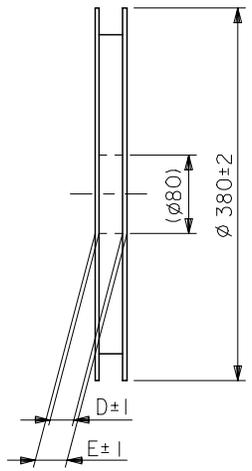
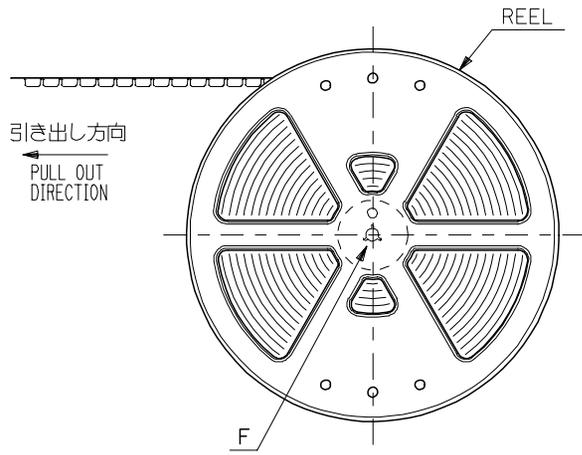
補強フィルム材質はポリイミドを推奨します。ベースフィルムは25μmを推奨します。
接着剤は熱硬化接着剤を推奨します。
尚、接着剤の接点部への付着は導通不良の原因になりますので、染み出しが無い様、お願い致します。

ABOUT FPC
RECOMMENDED MATERIAL/THICKNESS.
STIFFENER FILM : POLYIMIDE
BASE FILM THICKNESS : 25μm
BONDING AGENT : THERMOSETTING BONDING AGENT
PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON THE CONTACT AREA BECAUSE THE EXTRA ADHESIVE MAY CAUSE THE DEFECT IN ELECTRICAL CONTINUITY.

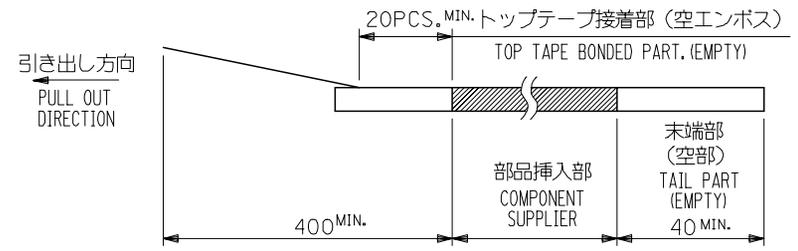
REVISED EC NO: J2008-4048 DRWN:WABEI 2008/06/13 CHKD:THARUYAMA 2008/06/16 APPR:NUKITA 2008/06/16	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	54548-**19	MODEL No.	
							DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	±0.2	DRAWN BY Y. WADA	DATE 2004/01/09	TITLE 0.5 FPC CONN ZIF HSG ASSY FOR SMT RA BTM CONT -LEAD FREE-			
		10 OVER 30 UNDER	±0.25	CHECKED BY M. SASAO	DATE 2004/01/09	MOLEX INCORPORATED			
		30 OVER	±0.3	APPROVED BY M. SASAO	DATE 2004/01/09	DOCUMENT NO. SD-54548-037			
		ANGULAR ±3 °		MATERIAL NO. SEE SHEET 1		SHEET NO. 2 OF 2			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

NOTES

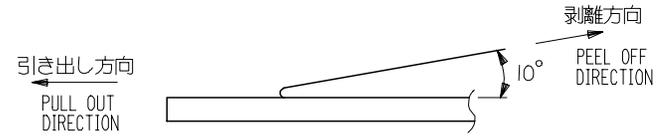
- 製品詳細寸法については図面 SD-54548-037 を参照下さい。
RE DETAILED DIMENSION, SEE SD-54548-037.
- 梱包数量：3000個/リール
NUMBER OF CONNECTORS : 3000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH



DETAIL F



- トップテープの剥離強度：0.1N ~ 1.3N { 10gf ~ 130gf }
(剥離方向は下図参照)
尚、本規格値は出荷時に適用。(但し、輸送時に剥離が発生しないこと。)
PEELING OFF FORCE OF TOP TAPE : 0.1N ~ 1.3N (10gf ~ 130gf)
(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT.
PEEL OFF SHOULD NOT BE ALLOWED , DURING TRANSPORTATION.



- 材料 (MATERIAL)
キャリアテープ (CARRIER TAPE) : ポリプロピレン (POLYPROPYLENE)
トップテープ (TOPTAPE) : PET, PE, PEF
リール (REEL) : ポリスチレン (PS) <リサイクル材を含む>
POLYSTYRENE (PS) <RECYCLE MATERIAL CONTAINED>
- 本製品は54548-**-90の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 54548-**-90.

REVISED EC NO: J2005-2516 DRAWN: NABEI 2005/02/28 CHYKD: TOYODA 2005/02/28 APPR: NUKITA 2005/03/07	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		54548-**-70	MODEL NO.
	10 UNDER	± 0.2	DRAWN BY	DATE	SCALE ---	DESIGN UNITS METRIC
	10 OVER 30 UNDER	± 0.25	Y. WADA	2004/01/09	TITLE	EMBSTP PKG FOR 0.5 FPC CONN ZIF HSG ASSY -LEAD FREE-
	30 OVER	± 0.3	M. SASAO	2004/01/09	MOLEX INCORPORATED MOLEX	
	ANGULAR	$\pm 3^\circ$	APPROVED BY	DATE	MATERIAL NO.	DOCUMENT NO.
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		M. SASAO	2004/01/09	SEE CHART	SD-54548-038	1 OF 4

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

10 9 8 7 6 5 4 3 2 1

F

E

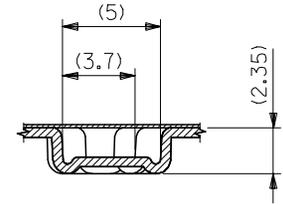
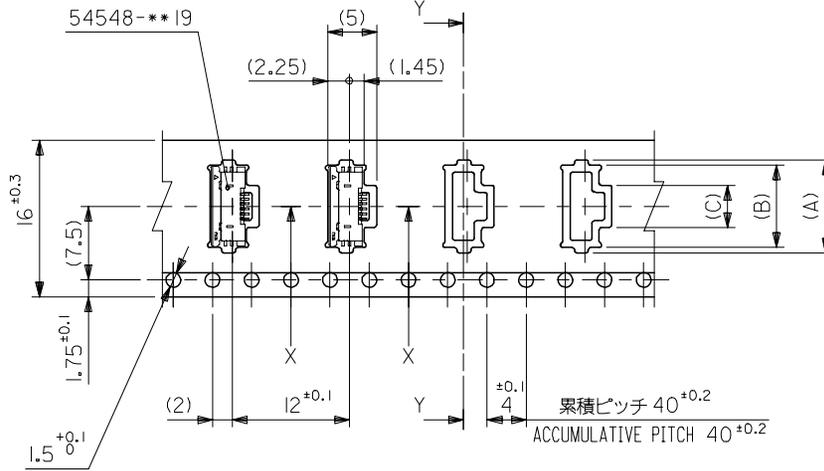
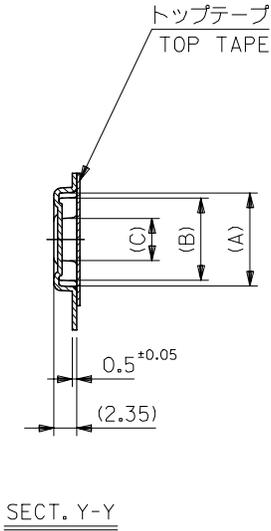
D

C

B

A

引き出し方向
PULL OUT DIRECTION



SECT. X-X

16mm幅キャリアテープ
16mm WIDTH CARRIER TAPE

16	21.4	17.4	4.3	8.4	9.5	54548-0670	6
			3.8	7.9	9	54548-0570	5
			3.3	7.4	8.5	54548-0470	4
キャリアテープ幅 CARRIER TAPE WIDTH	E	D	(C)	(B)	(A)	製品番号 MATERIAL No.	極数 CIRCUIT

54548-***70 MODEL NO.

REVISED EC No: J2005-2516 2005/02/28 DRAWN: NABEI 2005/02/28 CHKD: KTOYODA 2005/03/07 APPR: NUKITA	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY Y. WADA		DATE 2004/01/09		TITLE EMBSTP PKG FOR 0.5 FPC CONN ZIF HSG ASSY -LEAD FREE-	
	10 OVER 30 UNDER	±0.25	CHECKED BY M. SASAO		DATE 2004/01/09		MOLEX INCORPORATED	
	30 OVER	±0.3	APPROVED BY M. SASAO		DATE 2004/01/09		DOCUMENT NO. SD-54548-038	
	ANGULAR	±3 °	MATERIAL NO. SEE CHART		SHEET NO. 2 OF 4		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS								

9

8

7

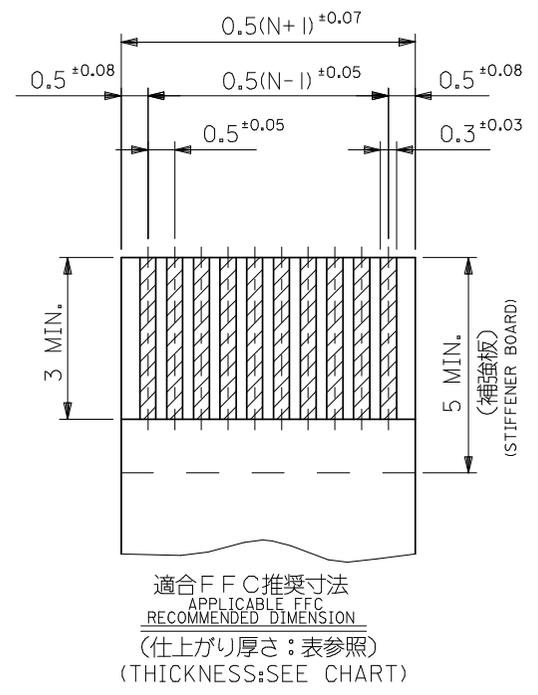
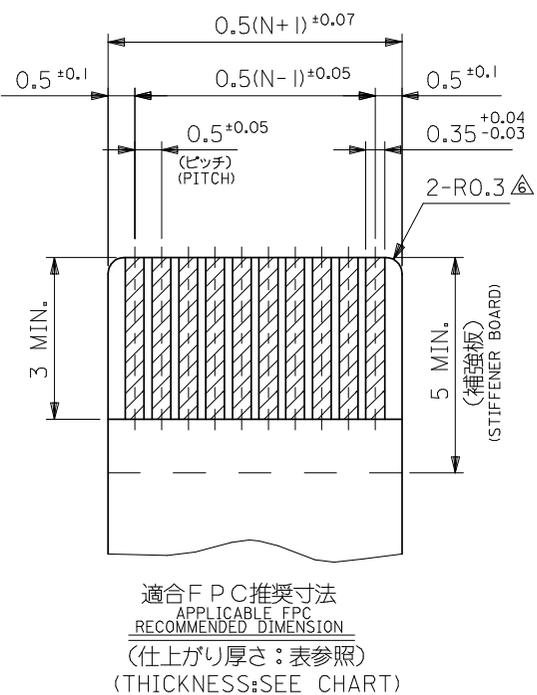
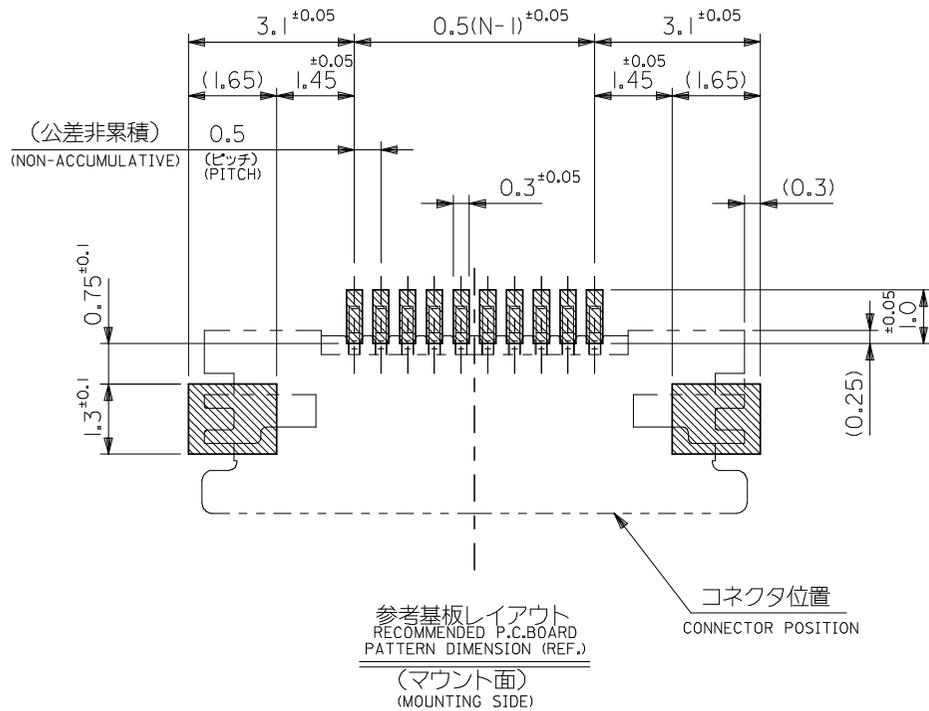
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4

3

2



適合FPC推奨寸法
APPLICABLE FPC
RECOMMENDED DIMENSION
(仕上がり厚さ:表参照)
(THICKNESS:SEE CHART)

適合FFC推奨寸法
APPLICABLE FFC
RECOMMENDED DIMENSION
(仕上がり厚さ:表参照)
(THICKNESS:SEE CHART)

注記 NOTES

- I. 使用材料 MATERIAL
- ハウジング : LCP, UL94V-0
 - アクチュエータ : PPS, UL94V-0
 - ターミナル : リン青銅 (t=0.2)
 - メッキ : 接点部:金メッキ
 - テール部: 鍍メッキ
 - 金具 : リン青銅、鍍メッキ (t=0.2)

- △パターンはくり止め用金具
- △RO.3はFPC導体部にかからないこと
- 7.本製品は54548-**-21の鉛フリー(部分金メッキ)品である。
- 8. N: 極数 N: CIRCUIT.

2. エンボステープ梱包時は、アクチュエータがロックした状態とする。
- △ソルダーテール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面 Z に対し上方向 OMAX.、下方向 0.15MAX.とし、相互のバラツキ量は0.1MAX.とする。
- △偶数極に適用。

FPC/FFC について:

打ち抜き方向は導体側から補強板側を推奨します。
導体部については軟銅箔35μmまたは50μmを推奨します。
ABOUT FPC/FFC
RECOMMENDED PUNCHER DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.
RECOMMENDED CONDUCTOR SPEC :
THICKNESS OF SOFT COPPER FOIL : 35 MICROMETER OR 50 MICROMETER.

FPC について:

補強フィルム材質はポリイミドを推奨します。ベースフィルムは25μmを推奨します。
接着剤は熱硬化接着剤を推奨します。
尚、接着剤の接点部への付着は導通不良の原因になりますので、染み出しが無い様、お願い致します。
ABOUT FPC
RECOMMENDED MATERIAL/THICKNESS.
STIFFENER FILM : POLYIMIDE
BASE FILM THICKNESS : 25μm
BONDING AGENT : THERMOSETTING BONDING AGENT
PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON THE CONTACT AREA BECAUSE THE EXTRA ADHESIVE MAY CAUSE THE DEFECT IN ELECTRICAL CONTINUITY.

REVISED EC NO: J2008-4048 DRWN:WABEI CHKD:THARYAMA APPR:NUKITA	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	MODEL No. 54548-**-29	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY HSHIMABUKURO	DATE '04/02/10	TITLE 0.5 FPC CONN ZIF HSG ASSY FOR SMT RA BTM CONT -LEAD FREE-			
	10 OVER 30 UNDER	±0.25	CHECKED BY KTOJO	DATE '04/02/10	APPROVED BY MSASAO			
	30 OVER	±0.3	DATE '04/02/10	MATERIAL NO. SEE SHEET 1				
	ANGULAR	±3	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		DOCUMENT NO. SD-54548-039		SHEET NO. 2 OF 2	
N	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							

10 9 8 7 6 5 4 3 2 1

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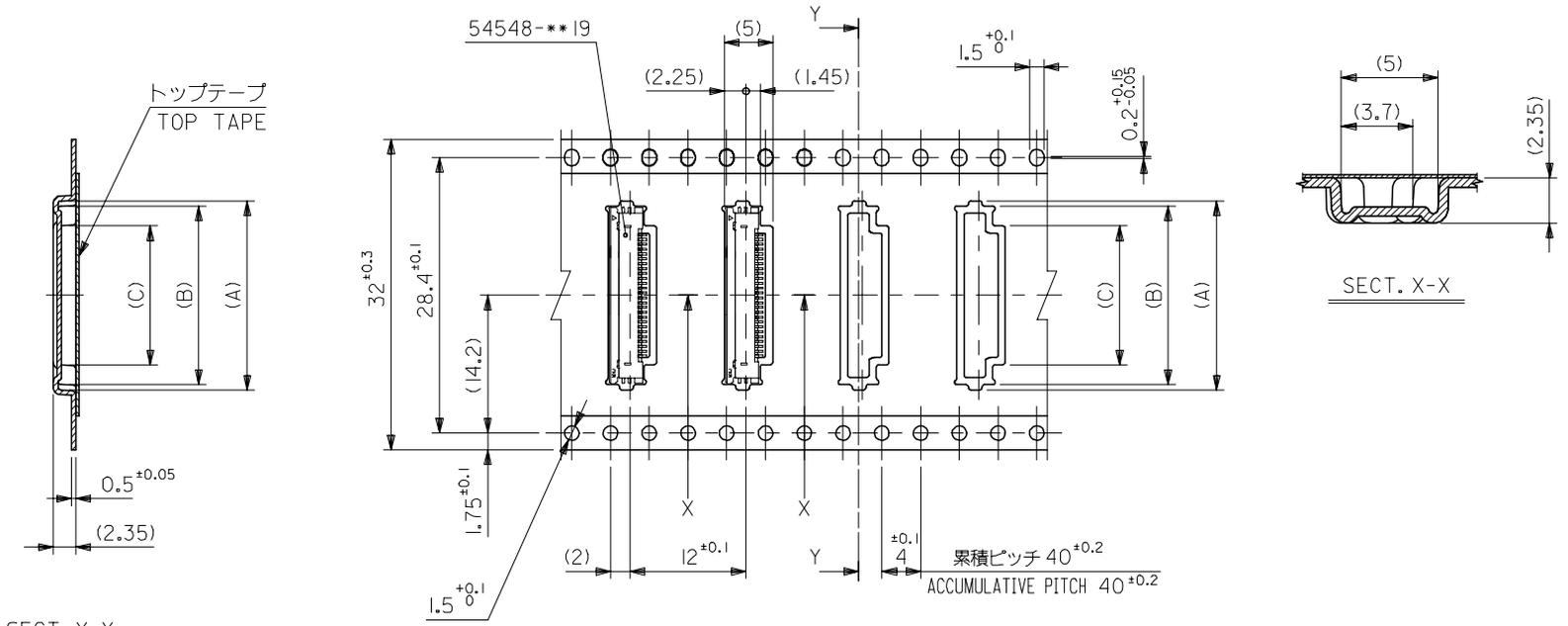
D

C

B

A

引き出し方向
PULL OUT DIRECTION



SECT. Y-Y

SECT. X-X

32mm幅キャリアテープ
32mm WIDTH CARRIER TAPE

32	37.4	33.4	14.3	18.4	19.5	54548-2670	26
キャリアテープ幅 CARRIER TAPE WIDTH	E	D	(C)	(B)	(A)	54548-2470	24
						製品番号 MATERIAL No.	極数 CIRCUIT

REVISED EC NO: J2005-2516 DRAWN: NABEI CHKD: KTOYODA APPR: NUKITA	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY Y. WADA	DATE 2004/01/09	TITLE EMBSTP PKG FOR 0.5 FPC CONN ZIF HSG ASSY -LEAD FREE-		
	10 OVER 30 UNDER	±0.25	CHECKED BY M. SASAO	DATE 2004/01/09			
	30 OVER	±0.3	APPROVED BY M. SASAO	DATE 2004/01/09			
	ANGULAR	±3 °	MATERIAL NO.		DOCUMENT NO. SD-54548-038		SHEET NO. 4 OF 4
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		MOLEX INCORPORATED THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			